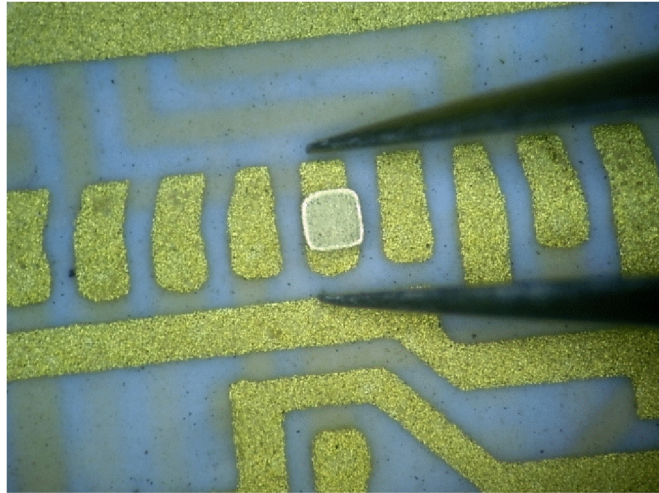


bonding source



About the Bonding Shims:

Molybdenum Characteristics:

- Low coefficient of thermal expansion (5.1×10^{-6} m/m/°C) which is about half that of most steels
- Good thermal conductivity
- Good electrical conductivity
- Good stiffness, greater than that of steel (Young's Modulus 317MPa)
- High melting point (2615°C)
- Good hot strength
- Good strength and ductility at room temperature
- High density (10.2 g/cm³)

The "moly shim" is plated with 50 microinches of nickel minimum, under 50 microinches minimum of gold.

The shims are typically soldered to the circuit board or epoxied with electrically conductive epoxy. Once attached to the circuit or substrate, you can wire bond or solder to the top of the shim. It's great to have a vial of these in the assembly area in the event you get solder on a bond site, damage a trace, or need a standoff.

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